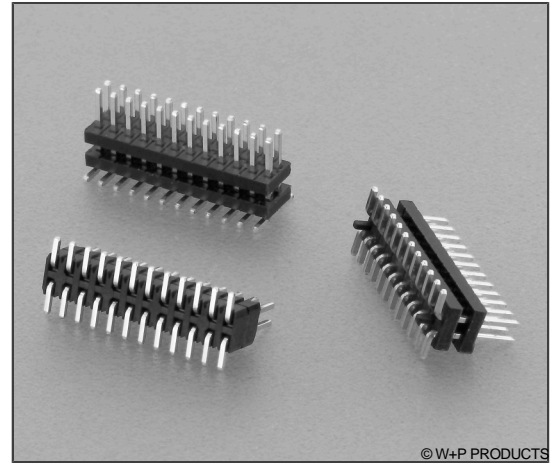


SMT-Sandwich-Stiftleisten RM 1,27mm, 2-reihig – 1,0-2,5mm Isolierkörper SMT Dual Body Pin Headers, 1.27mm Pitch, Double Row – 1.0-2.5mm Body

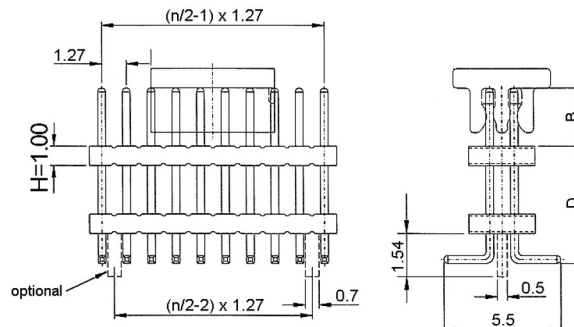
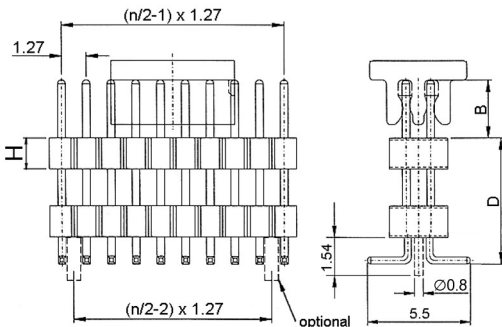
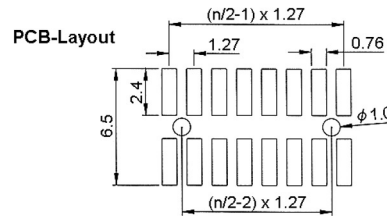
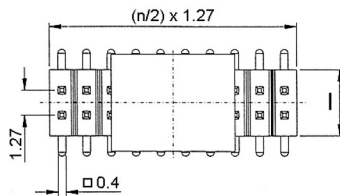
Technische Daten / Technical Data

| | |
|-----------------------|---------------------------------------|
| Isolierkörper | Thermoplast, nach UL94 V-0 |
| Insulator | Thermoplastic, rated UL94 V-0 |
| Kontaktmaterial | Vierkantstift 0,40mm, Kupferlegierung |
| Contact Material | 0.40mm square pin, copper alloy |
| Kontaktoberfläche | Lt. Oberflächenoptionen, über Ni |
| Contact Surface | Acc. to options (see below), over Ni |
| Durchgangswiderstand | < 20 mΩ |
| Contact Resistance | < 20 mΩ |
| Isolationswiderstand | > 500 MΩ |
| Insulation Resistance | > 500 MΩ |
| Spannungsfestigkeit | 500 V AC |
| Test Voltage | 500 V AC |
| Nennspannung | 250 V AC |
| Voltage Rating | 250 V AC |
| Nennstrom | 1 A |
| Current Rating | 1 A |
| Temperaturbereich | -40 °C ... +105 °C |
| Temperature Range | -40 °C ... +105 °C |
| Verarbeitung | Reflow-Lötverfahren |
| Processing | Reflow soldering |



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Passende Buchsenleisten:
Compatible Female Headers:
6060 6061 6062 etc.
Weitere siehe Kapitel B
Please see ch. B for more



| Series | Contacts* | Insulator* | Dimensions* | Locating Pegs* | Plating* | Packaging* |
|-------------|--|---|---|---|---|--|
| 7073 | 100 004-100 Zweireihig Double row | 16 10 H=1,00 l=3,40mm, Loc. Pegs 0.7x0.5mm optional 16 H=1,60 l=3,00mm No Loc. Pegs 25 H=2,50 l=3,00mm No Loc. Pegs 40 H=2,51 l=3,43mm, Loc. Pegs Ø0.8mm optional | 30 20 B=3,00 D=3,60mm 30 B=3,00 D=9,80mm 40 B=3,00 D=10,40mm 99- Kundenspezifisch Customer-specific | 00 00 Ohne Pos.hilfen W/o loc. pegs 10 Mit Pos.hilfen With loc. pegs | 00 00 Vergoldet Gold plated 60 Sel. Au/Sn Duplex plating | ST ST PPST PPTR (Option) |

Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads
PPST In Stangen mit P&P-Pads / In tubes with P&P-Pads
PPTR (Option) Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Informationen zum Reflow-Lötverfahren Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

| Profileigenschaft | Kennwert |
|--------------------------------------|---------------|
| Temperatur Minimum T_{Smin} | 150 °C |
| Temperatur Maximum T_{Smax} | 200 °C |
| Dauer $T_{Smin} - T_{Smax}$ | 60 – 180s |
| Temperatur Lötbereich T_L | 217 °C |
| Verweildauer oberhalb T_L | 60 – 180s |
| Ramp-Up Rate $T_{Smax} - T_P$ | max. 3 °C / s |
| Höchsttemperatur T_P | 260±5 °C |
| Dauer Höchsttemperatur | 20 – 40s |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6 °C / s |
| Dauer 25 °C – Höchsttemperatur T_P | max. 8m |

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

| Profile Feature | Key Values |
|--------------------------------------|---------------|
| Minimum Temperature T_{Smin} | 150 °C |
| Maximum Temperatur T_{Smax} | 200 °C |
| Duration $T_{Smin} - T_{Smax}$ | 60 – 180s |
| Soldering Range Temperature T_L | 217 °C |
| Duration above T_L | 60 – 180s |
| Ramp-Up Rate $T_{Smax} - T_P$ | max. 3 °C / s |
| Peak Temperature T_P | 260±5 °C |
| Duration Peak Temperature | 20 – 40s |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6 °C / s |
| Duration 25°C - Peak Temp. T_P | max. 8min |

